



Material Content Data Sheet



Sales Product Name		BSD840N H6327		Issued		20. July 2018		
MA#		MA001627316						
Package		PG-SOT363-6-1		Weight*		6.30 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.002	0.04		394	
	noble metal	gold	7440-57-5	0.010	0.15		1528	
	inorganic material	silicon	7440-21-3	0.147	2.33	2.52	23314	25236
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		91	
	non noble metal	titanium	7440-32-6	0.003	0.05		458	
	non noble metal	chromium	7440-47-3	0.009	0.14		1373	
	non noble metal	copper	7440-50-8	2.869	45.57	45.77	455678	457600
wire	non noble metal	copper	7440-50-8	0.010	0.16	0.16	1579	1579
encapsulation	organic material	carbon black	1333-86-4	0.030	0.47		4728	
	plastics	epoxy resin	-	0.640	10.16		101650	
	inorganic material	silicondioxide	60676-86-0	2.307	36.64	47.27	366414	472792
leadfinish	non noble metal	tin	7440-31-5	0.213	3.39	3.39	33865	33865
plating	noble metal	silver	7440-22-4	0.056	0.89	0.89	8928	8928
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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